

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3122486

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KUEI-SUNG CHANG	01/28/2013
CHUN-WEN CHENG	01/28/2013
ALEX KALNITSKY	01/30/2013
CHIA-HUA CHU	01/28/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14551874
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	2012-0698-D / 24061.3051
NAME OF SUBMITTER:	KYLE HOWARD
SIGNATURE:	/KYLE HOWARD/
DATE SIGNED:	11/25/2014
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Kuei-Sung Chang | of | #207, Fl. 12, Wu-Miao Road
Lin-Ya District, Kaohsiung City
Taiwan (R.O.C.) |
| (2) | Chun-Wen Cheng | of | No. 15, Alley 11, Lane 100, Jiafeng 1st Street
Zhubei City, Hsinchu County 302
Taiwan (R.O.C.) |
| (3) | Alex Kalnitsky | of | 737 La Playa #B, San Francisco, CA, 94121 |
| (4) | Chia-Hua Chu | of | No. 1, Lane 176, Aikou 6th Street
Zhubei City, Hsinchu County 302,
Taiwan (R.O.C.) |

have invented certain improvements in

INTEGRATED SEMICONDUCTOR DEVICE AND WAFER LEVEL METHOD OF FABRICATING THE SAME

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application number ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Kuei-Sung Chang

Residence Address: #207, Fl. 12, Wu-Miao Road, Lin-Ya District
Kaohsiung City, Taiwan (R.O.C.)

Dated: ✓ 2013/1/28

✓ Kuei-Sung Chang
Inventor Signature

Inventor Name: Chun-Wen Cheng

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Dated: ✓ 2013.01.28

✓ Chun-Wen Cheng
Inventor Signature

Inventor Name: Alex Kalnitsky

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Dated: ✓ Alex Kalnitsky

✓ 1/30/2013
Inventor Signature

Docket No.: 2012-0698 / 24061.2270
Customer No.: 000042717

Inventor Name: Chia-Hua Chu

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Dated: ✓ 2013. 1. 28

✓ CHIA-HUA CHU
Inventor Signature
